



IFW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Richard W. Wensel

Serial No.: 10/600,149

Filed: June 19, 2003

For: SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK AND
TRANSFER MOLD

Examiner: N. Ha

Group Art Unit: 2811

Attorney Docket No.: 2269-3061.8US
(96-0893.07/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

August 3, 2004
Date

Signature

Deborah L. Hendricks
Name (Type/Print)

AMENDMENT

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This amendment is in response to the Office Action of May 4, 2004 whose initial period of response is set to expire on August 4, 2004.

The listing of claims begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.